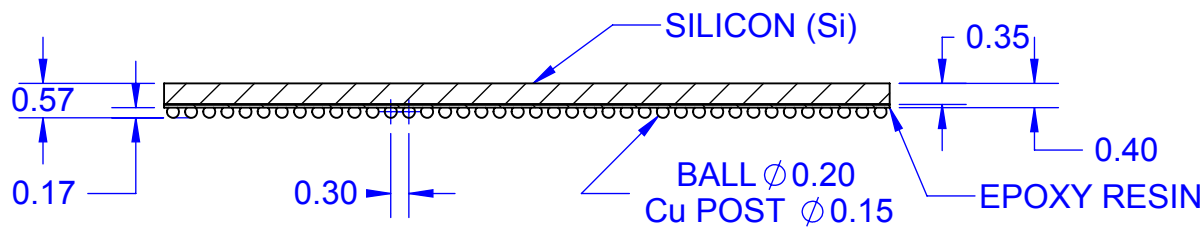
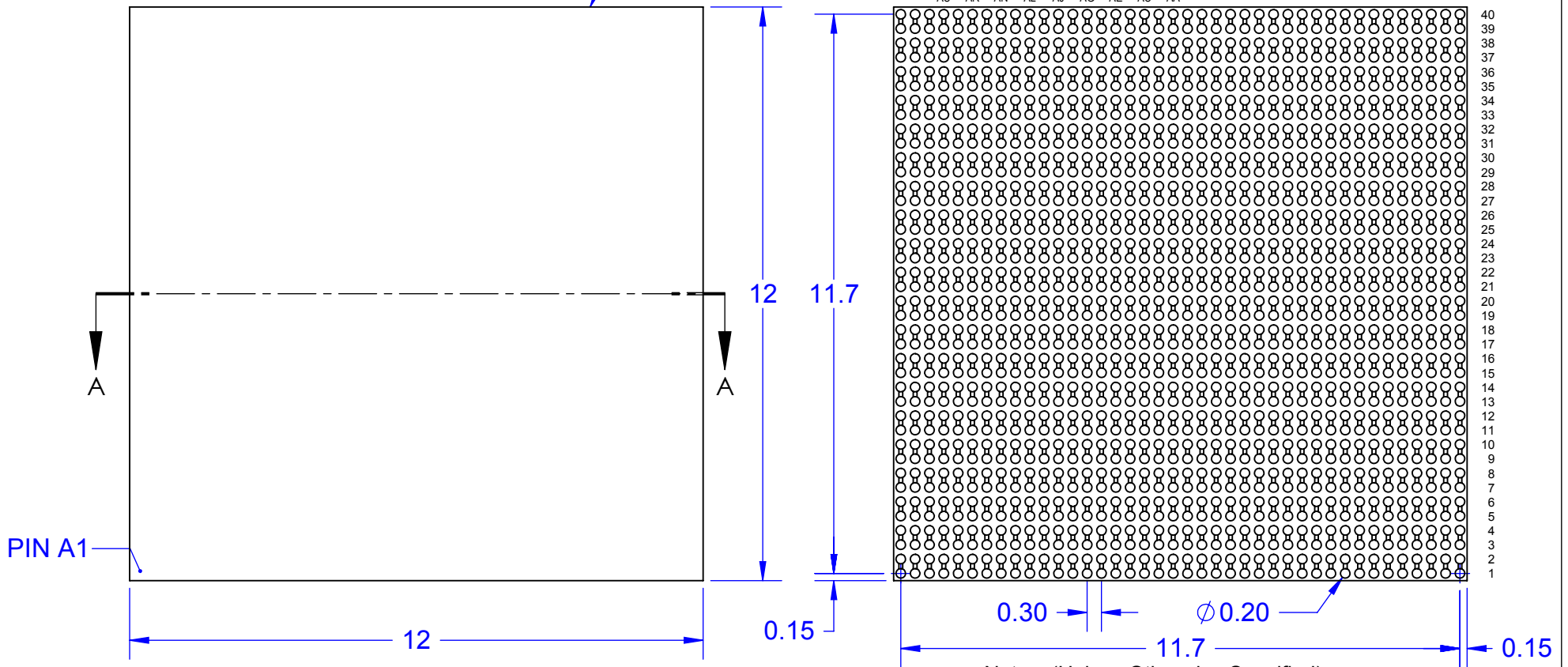


TOP VIEW

SILICON (Si)

BALL VIEW




SECTION A-A

Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY:
STANDARD: SAC305 (Sn96.5/Ag3.0/Cu0.5).
SPECIAL: LF53 (Sn98.3/Ag1.2/Cu0.5).
- 3) BALL DIAMETER (BEFORE REFLOW): 0.20mm.
- 4) NON-SOLDER MASK DEFINED PAD.
- 5) PAD Cu DIAMETER: 0.15mm.
- 6) SUBSTRATE MATERIAL: Si (SILICON).
- 7) DAISY CHAIN PATTERN (SEE PAGE 2).

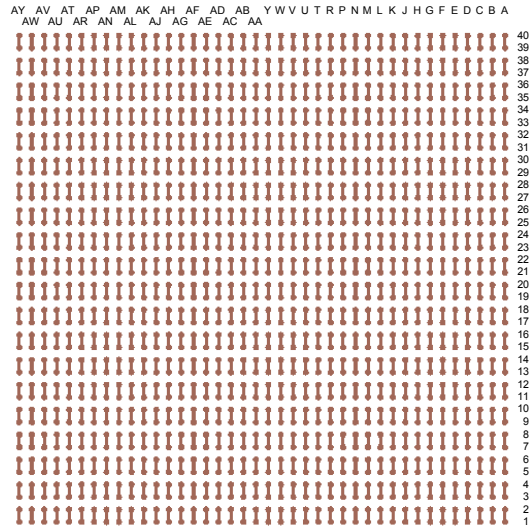
PART NUMBER TABLE

PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
WLP1600T.3C-DC407D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
WLP1600T.3C1-DC407D	Sn98.3/Ag1.2/Cu0.5	YES	YES	YES

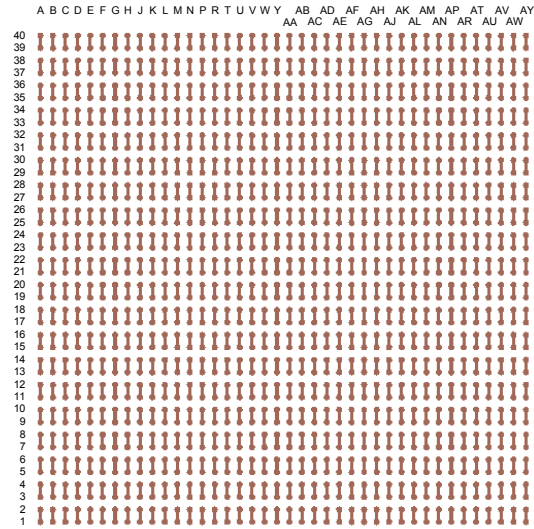
APPROVALS		DATE				
DRAWN	T. Au	10/28/12				
ENG	M. Hart	10/28/12	TITLE			
MFG			WLP1600T.3C-DC407D 1600 BALL P-0.3mm (TEG0306)			
QA			SCALE	SIZE	DRAWING NO.	REV
CUST				A	534070	A
REVISED			DO NOT SCALE DRAWING			SHEET 1 OF 2

DAISY CHAIN PATTERN

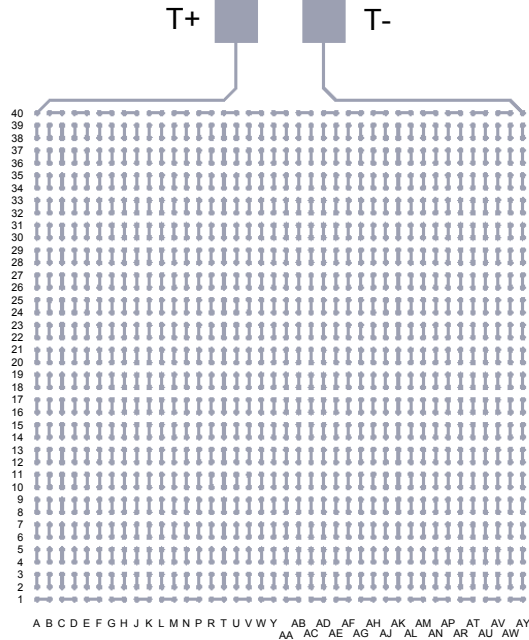
BALL VIEW



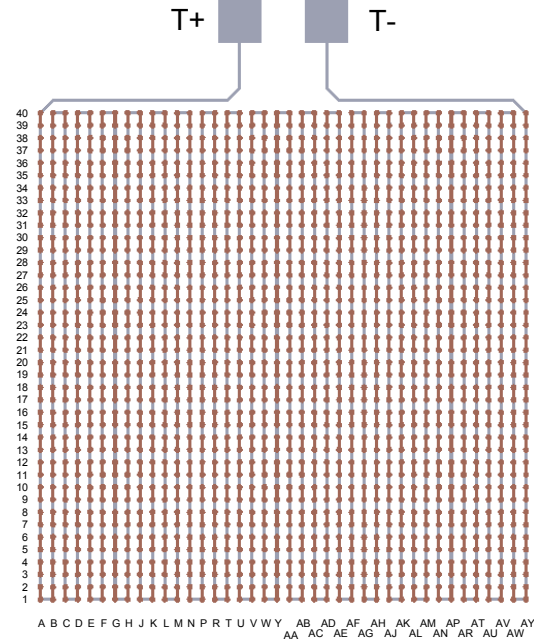
BOTTOM SIDE
(TOP X-RAY VIEW)



TOP VIEW



AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.15mm (5.9mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.07mm (3mil).



TITLE			
WLP1600T.3C-DC407D 1600 BALL P-0.3mm (TEG0306)			
SCALE	SIZE	DRAWING NO.	REV
	A	534070	A
DO NOT SCALE DRAWING			SHEET 2 OF 2